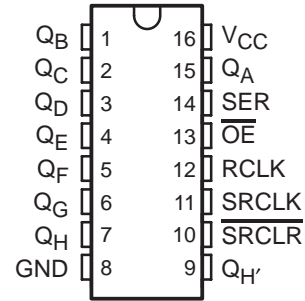


CD74HC595 8-BIT SHIFT REGISTERS WITH 3-STATE OUTPUT REGISTERS

SCHS353 – JANUARY 2004

- 8-Bit Serial-In, Parallel-Out Shift
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 14$ ns
- ± 6 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- Shift Register Has Direct Clear

DW, E, M, NS, OR SM PACKAGE
(TOP VIEW)



description/ordering information

The CD74HC595 device contains an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state outputs. Separate clocks are provided for both the shift and storage registers. The shift register has a direct overriding clear (\overline{SRCLR}) input, serial (SER) input, and serial output for cascading. When the output-enable (\overline{OE}) input is high, the outputs are in the high-impedance state.

Both the shift register clock (SRCLK) and storage register clock (RCLK) are positive-edge triggered. If both clocks are connected together, the shift register always is one clock pulse ahead of the storage register.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	PDIP – E	Tube of 25	CD74HC595E	CD74HC595E
	SOIC – DW	Tube of 40	CD74HC595DW	HC595M
		Reel of 2000	CD74HC595DWR	
	SOIC – M	Tube of 40	CD74HC595M	HC595M
		Reel of 2500	CD74HC595M96	
		Reel of 250	CD74HC595MT	
	SOP – NS	Reel of 2000	CD74HC595NSR	HC595M
	SSOP – SM	Tube of 80	CD74HC595SM	HJ595
Reel of 2000		CD74HC595SM96		

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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CD74HC595
8-BIT SHIFT REGISTERS
WITH 3-STATE OUTPUT REGISTERS

SCHS353 – JANUARY 2004

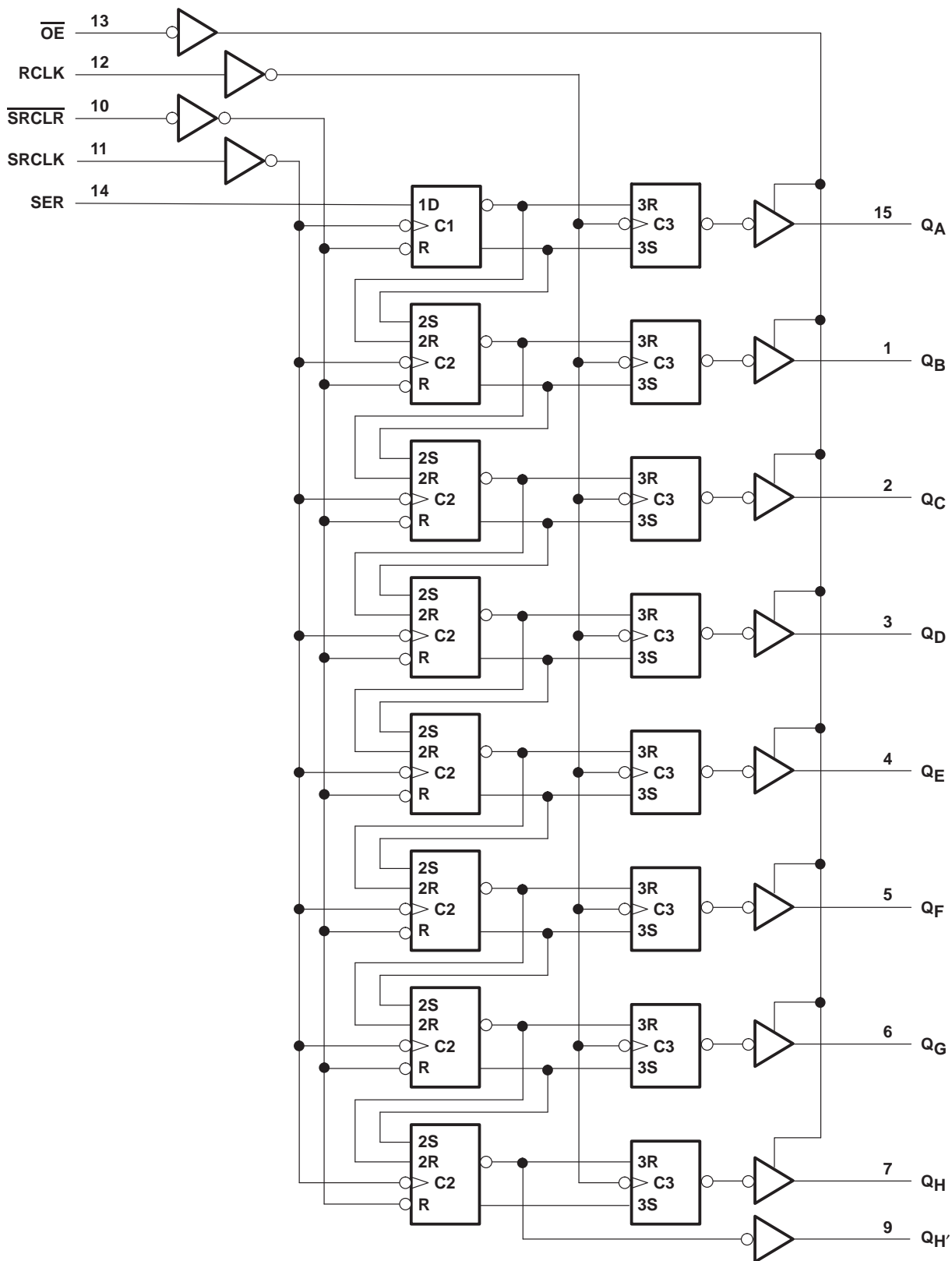
FUNCTION TABLE

INPUTS					FUNCTION
SER	SRCLK	SRCLR	RCLK	OE	
X	X	X	X	H	Outputs Q _A –Q _H are disabled.
X	X	X	X	L	Outputs Q _A –Q _H are enabled.
X	X	L	X	X	Shift register is cleared.
L	↑	H	X	X	First stage of the shift register goes low. Other stages store the data of previous stage, respectively.
H	↑	H	X	X	First stage of the shift register goes high. Other stages store the data of previous stage, respectively.
X	X	X	↑	X	Shift-register data is stored in the storage register.

CD74HC595
8-BIT SHIFT REGISTERS
WITH 3-STATE OUTPUT REGISTERS

SCHS353 – JANUARY 2004

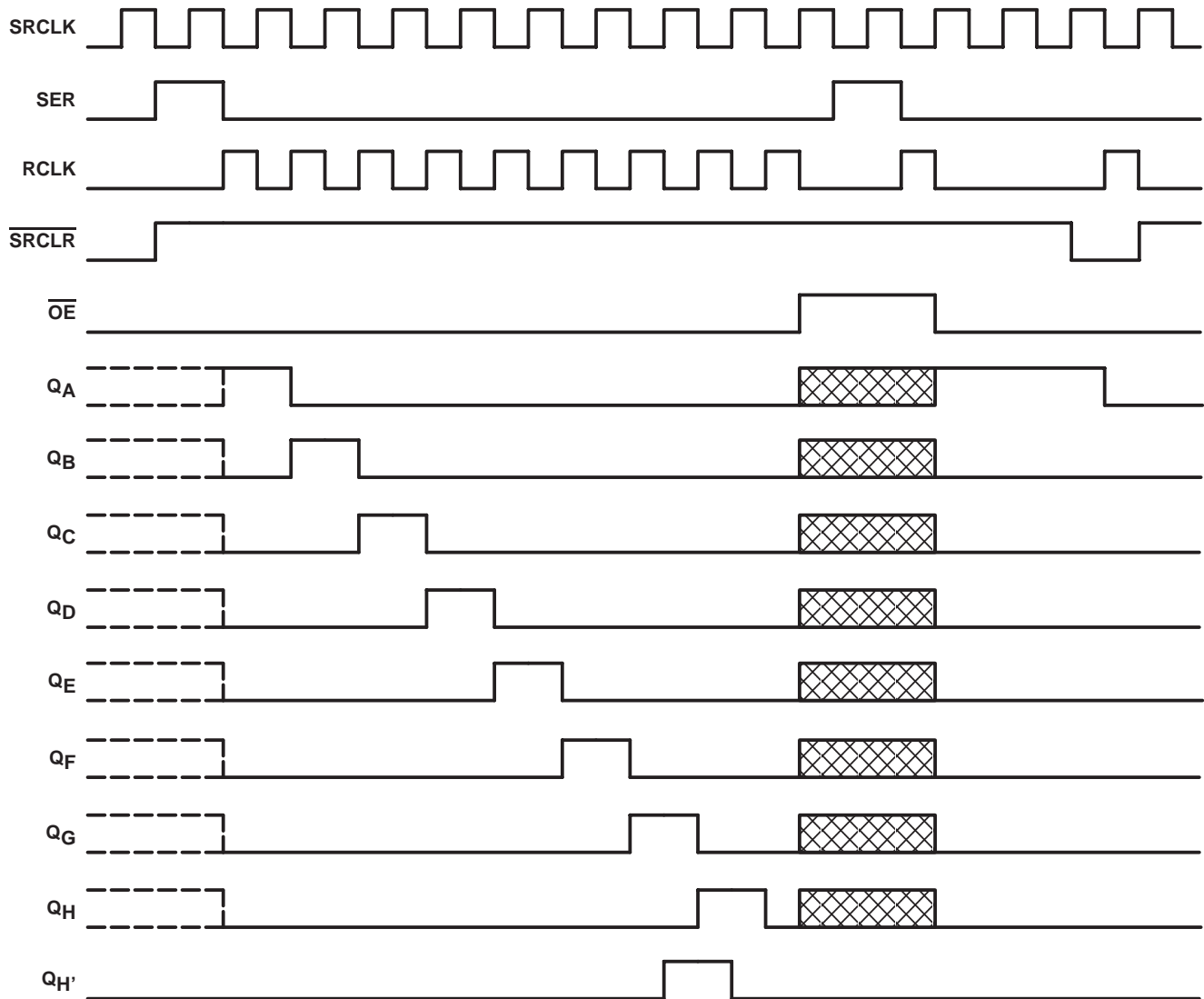
logic diagram (positive logic)




CD74HC595 8-BIT SHIFT REGISTERS WITH 3-STATE OUTPUT REGISTERS

SCHS353 – JANUARY 2004

timing diagram



NOTE:  implies that the output is in 3-State mode.

CD74HC595
8-BIT SHIFT REGISTERS
WITH 3-STATE OUTPUT REGISTERS
 SCHS353 – JANUARY 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V_{CC} or GND	±70 mA
Package thermal impedance, θ_{JA} (see Note 2): E package	67°C/W
DW package	57°C/W
M package	73°C/W
NS package	64°C/W
SM package	82°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.5		V
		$V_{CC} = 4.5$ V	3.15		
		$V_{CC} = 6$ V	4.2		
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V		0.5	V
		$V_{CC} = 4.5$ V		1.35	
		$V_{CC} = 6$ V		1.8	
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
$\Delta t/\Delta v$ ‡	Input transition rise/fall time	$V_{CC} = 2$ V		1000	ns
		$V_{CC} = 4.5$ V		500	
		$V_{CC} = 6$ V		400	
T_A	Operating free-air temperature	–55		125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

‡ If this device is used in the threshold region (from $V_{ILmax} = 0.5$ V to $V_{IHmin} = 1.5$ V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at $t_f = 1000$ ns and $V_{CC} = 2$ V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.



CD74HC595
8-BIT SHIFT REGISTERS
WITH 3-STATE OUTPUT REGISTERS

SCHS353 – JANUARY 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	2 V	1.9	1.998		1.9		1.9	V
			4.5 V	4.4	4.499		4.4		4.4	
			6 V	5.9	5.999		5.9		5.9	
		4.5 V	Q _H ', I _{OH} = -4 mA	3.98	4.3		3.7		3.84	
			Q _A -Q _H , I _{OH} = -6 mA	3.98	4.3		3.7		3.84	
		6 V	Q _H ', I _{OH} = -5.2 mA	5.48	5.8		5.2		5.34	
			Q _A -Q _H , I _{OH} = -7.8 mA	5.48	5.8		5.2		5.34	
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	2 V		0.002	0.1		0.1	0.1	V
			4.5 V		0.001	0.1		0.1	0.1	
			6 V		0.001	0.1		0.1	0.1	
		4.5 V	Q _H ', I _{OL} = 4 mA		0.17	0.26		0.4	0.33	
			Q _A -Q _H , I _{OL} = 6 mA		0.17	0.26		0.4	0.33	
		6 V	Q _H ', I _{OL} = 5.2 mA		0.15	0.26		0.4	0.33	
			Q _A -Q _H , I _{OL} = 7.8 mA		0.15	0.26		0.4	0.33	
I _I	V _I = V _{CC} or 0	6 V		±0.1	±100		±1000	±1000	nA	
I _{OZ}	V _O = V _{CC} or 0, Q _A -Q _H	6 V		±0.01	±0.5		±10	±5	μA	
I _{CC}	V _I = V _{CC} or 0, I _O = 0	6 V			8		160	80	μA	
C _i		2 V to 6 V		3	10		10	10	pF	

CD74HC595
8-BIT SHIFT REGISTERS
WITH 3-STATE OUTPUT REGISTERS
 SCHS353 – JANUARY 2004

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V _{CC}	T _A = 25°C		T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	2 V	6		4.2		5		MHz
		4.5 V	31		21		25		
		6 V	36		25		29		
t _w	SRCLK or RCLK high or low	2 V	80		120		100		ns
		4.5 V	16		24		20		
		6 V	14		20		17		
	SRCLR low	2 V	80		120		100		
		4.5 V	16		24		20		
		6 V	14		20		17		
t _{su}	SER before SRCLK↑	2 V	100		150		125		ns
		4.5 V	20		30		25		
		6 V	17		25		21		
	SRCLK↑ before RCLK↑†	2 V	75		113		94		
		4.5 V	15		23		19		
		6 V	13		19		16		
	SRCLR low before RCLK↑	2 V	50		75		65		
		4.5 V	10		15		13		
		6 V	9		13		11		
	SRCLR high (inactive) before SRCLK↑	2 V	50		75		60		
		4.5 V	10		15		12		
		6 V	9		13		11		
t _h	Hold time, SER after SRCLK↑	2 V	0		0		0		ns
		4.5 V	0		0		0		
		6 V	0		0		0		

† This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

CD74HC595
8-BIT SHIFT REGISTERS
WITH 3-STATE OUTPUT REGISTERS

SCHS353 – JANUARY 2004

switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			2 V	6	26		4.2		5	MHz	
			4.5 V	31	38		21		25		
			6 V	36	42		25		29		
t _{pd}	SRCLK	Q _{H'}	2 V		50	160		240		200	ns
			4.5 V		17	32		48		40	
			6 V		14	27		41		34	
	RCLK	Q _A -Q _H	2 V		50	150		225		187	
			4.5 V		17	30		45		37	
			6 V		14	26		38		32	
t _{PHL}	$\overline{\text{SRCLR}}$	Q _{H'}	2 V		51	175		261		219	ns
			4.5 V		18	35		52		44	
			6 V		15	30		44		37	
t _{en}	$\overline{\text{OE}}$	Q _A -Q _H	2 V		40	150		225		187	ns
			4.5 V		15	30		45		37	
			6 V		13	26		38		32	
t _{dis}	$\overline{\text{OE}}$	Q _A -Q _H	2 V		42	200		300		250	ns
			4.5 V		23	40		60		50	
			6 V		20	34		51		43	
t _t		Q _A -Q _H	2 V		28	60		90		75	ns
			4.5 V		8	12		18		15	
			6 V		6	10		15		13	
		Q _{H'}	2 V		28	75		110		95	
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

switching characteristics over recommended operating free-air temperature range, $C_L = 150$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	RCLK	Q _A -Q _H	2 V		60	200		300		250	ns
			4.5 V		22	40		60		50	
			6 V		19	34		51		43	
t _{en}	$\overline{\text{OE}}$	Q _A -Q _H	2 V		70	200		298		250	ns
			4.5 V		23	40		60		50	
			6 V		19	34		51		43	
t _t		Q _A -Q _H	2 V		45	210		315		265	ns
			4.5 V		17	42		63		53	
			6 V		13	36		53		45	



CD74HC595
8-BIT SHIFT REGISTERS
WITH 3-STATE OUTPUT REGISTERS
SCHS353 – JANUARY 2004

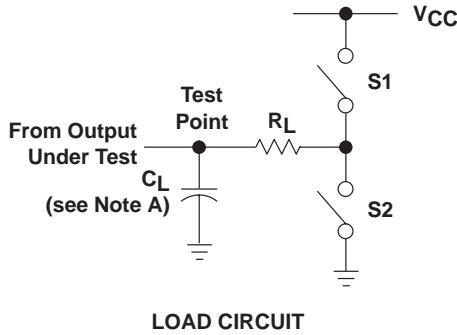
operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load	400	μF

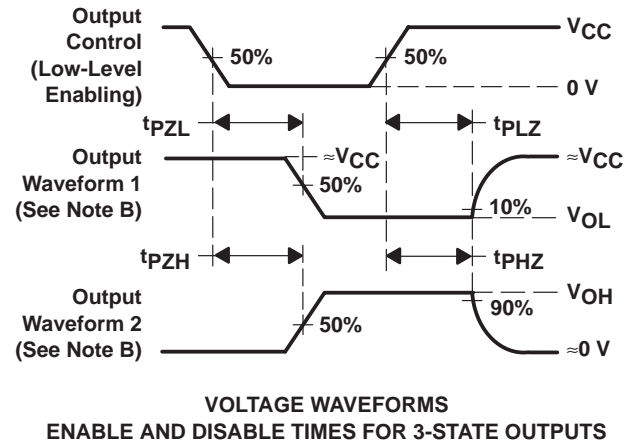
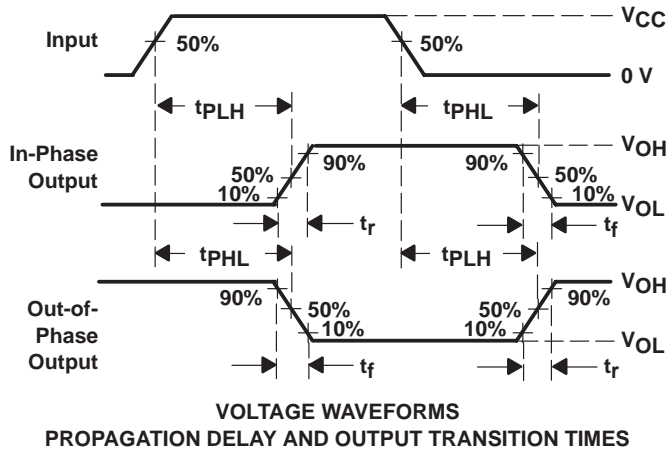
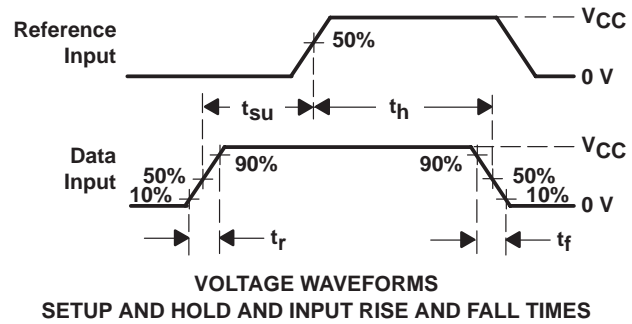
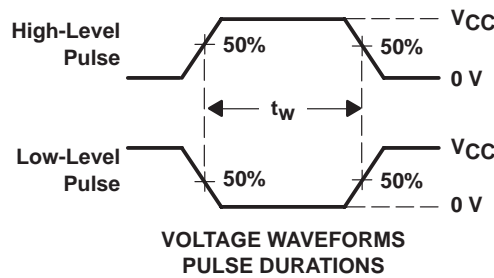
CD74HC595
8-BIT SHIFT REGISTERS
WITH 3-STATE OUTPUT REGISTERS

SCHS353 – JANUARY 2004

PARAMETER MEASUREMENT INFORMATION



PARAMETER	R_L	C_L	S1	S2
t_{en}	1 k Ω	50 pF or 150 pF	Open	Closed
			Closed	Open
t_{dis}	1 k Ω	50 pF	Open	Closed
			Closed	Open
t_{pd} or t_t	---	50 pF or 150 pF	Open	Open



- NOTES: A. C_L includes probe and test-fixture capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 D. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
 E. The outputs are measured one at a time, with one input transition per measurement.
 F. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 G. t_{PZL} and t_{PZH} are the same as t_{en} .
 H. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CD74HC595DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595DWE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595DWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595DWRE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595DWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC595EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC595M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CD74HC595NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595SM96	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595SM96E4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC595SM96G4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC595DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
CD74HC595M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC595NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC595SM96	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC595DWR	SOIC	DW	16	2000	367.0	367.0	38.0
CD74HC595M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HC595NSR	SO	NS	16	2000	367.0	367.0	38.0
CD74HC595SM96	SSOP	DB	16	2000	367.0	367.0	38.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211283-4/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AA.

DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4209202-2/E 07/11

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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